



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS5010-1EKB		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA001109432						
<b>Package</b>		PG-DSO-14-47		<b>Weight*</b>		150.81 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.015	2.66	2.66	26622	26622
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		115	
	non noble metal	zinc	7440-66-6	0.069	0.05		459	
	non noble metal	iron	7439-89-6	1.383	0.92		9174	
wire	non noble metal	copper	7440-50-8	56.175	37.25	38.23	372490	382238
	non noble metal	copper	7440-50-8	0.707	0.47	0.47	4689	4689
	organic material	carbon black	1333-86-4	0.167	0.11		1105	
encapsulation	plastics	epoxy resin	-	7.669	5.09		50851	
	inorganic material	silicondioxide	60676-86-0	75.521	50.06	55.26	500773	552729
leadfinish	non noble metal	tin	7440-31-5	2.472	1.64	1.64	16389	16389
plating	noble metal	silver	7440-22-4	1.470	0.98	0.98	9750	9750
glue	plastics	epoxy resin	-	0.200	0.13		1327	
	noble metal	silver	7440-22-4	0.943	0.63	0.76	6256	7583
*deviation	< 10%				Sum in total:	100,00		1000000

### Important Remarks:

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